Claims

1. Method for disposing a conductor structure (2) on a substrate (1) with the following method steps:

a) Establishing a separable connection (4) between at least one transfer support (3) and the conductor structure (2),

b) Joining together the transfer support (3) with the conductor structure (2) and the substrate (1), so that a connection (5) between the conductor structure (2) and the substrate (1) is established which is stronger than the separable connection (4) between the transfer support (3) and the conductor structure, and

c) Separating the separable connection (4) between the transfer support (3) and the conductor structure (2) of the transfer support (3), with the connection (5) being left between the conductor structure (2) and the substrate (1).

2. Method in accordance with claim 1, with a conductor structure (2) being used which features nanotubes (20).

3. Method in accordance with claim 2, with a conductor structure (2) being used in which the nanotubes (20) in at least one section of the conductor structure (2) are aligned essentially along one preferred direction (22).

4. Method in accordance with claim 2 or 3, with the nanotubes (20) being selected at least from the group of aluminum nitride, boron nitride and/or carbon nanotubes.

5. Method in accordance with one of the claims 2 to 4, with a conductor structure (2) being used which is formed by one type of nanotube.

6. Method in accordance with one of the claims 2 to 5, with nanotubes (20) being used which feature at least one

functionalized point.

7. Method in accordance with one of the claims 1 to 6, with a transfer support (3) with at least one transfer support substance (33) being used, which features at least one transfer support contact point for establishing the separable connection (4) between the transfer support (3) and the conductor structure (2).

8. Method in accordance with claim 7, with a transfer support substance (33) being used which is functionalized for creating the transfer support contact point at a point of the transfer support substance (33).

9. Method in accordance with claim 8, with a functionalized point of the transfer support substance (33) being used which features at least one sulfur atom.

10. Method in accordance with one of the claims 7 to 9, with a macro molecule being used as transfer support substance (33).

11. Method in accordance with claim 10, with at least one macro molecule being selected from the group deoxyribonucleic acid and/or protein.

12. Method in accordance with claim 10 or 11, with a macro molecule stretched lengthwise being used.

13. Method in accordance with one of the claims 10 to 12, with a folded macro molecule being used which is stretched before being joined together with the conductor structure.

14. Method in accordance with claim 13, with the folded macro molecule being stretched with the aid of a flowing fluid.

15. Method in accordance with one of the claims 1 to 14, with a substrate (1) with at least one substrate contact surface (10, 11) being used to establish the connection between the conductor structure (2) and the substrate (1).

16. Method in accordance with claim 15, with, before the transfer support (3) and the conductor structure (2) and the substrate (1) are joined together, at least one section of the substrate surface (14) being functionalized to establish the substrate contact surface (10, 11).

17. Method in accordance with claim 16, with gold being applied to establish the substrate contact surface (10, 11) on the section of the substrate surface (14).

18. Method in accordance with one of the claims 1 to 17, with an adhesive layer (35) being used to influence the firmness of the separable connection (4) between the transfer support (3) and the conductor structure (2) and/or connection (5) between the conductor structure (2) and the substrate (1).

19. Method in accordance with one of the claims 1 to 18, with at least one substrate (1) selected from the group semiconductor substrate and/or plastic substrate being used.

20. Substrate (1) with a conductor structure (2) which is connected to a substrate contact surface (10, 11) of the substrate (1) and to at least one further substrate contact surface (11, 10) of the substrate (1) with the substrate (1),

characterized in that,

the conductor structure (2) between the two substrate contact surfaces (10, 11) features nanotubes (20) which are aligned from the substrate contact surface (10, 11) to the further substrate contact surface (11, 10).

21. Substrate in accordance with claim 20, with the conductor structure (2) being an electrical conductor structure.

22. Substrate in accordance with claim 20 or 21, with the nanotubes (20) being selected from at least the group of aluminum nitride, boron nitride or carbon nanotubes.

23. Substrate in accordance with one of the claims 20 to 22, with the nanotubes (20) being one type of nanotube.

24. Substrate in accordance with one of the claims 20 to 23, with the substrate (1) featuring substrate material selected from the group semiconductor material and/or plastic material.